



Material Content Data Sheet



Sales Product Name		BSC026N02KS G		Issued		24. January 2018		
MA#		MA001280868						
Package		PG-TDSON-8-1		Weight*		121.54 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.410	2.81	2.81	28055	28055
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		311	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		93	
	non noble metal	copper	7440-50-8	37.762	31.06	31.10	310690	311094
wire	non noble metal	copper	7440-50-8	0.036	0.03	0.03	295	295
encapsulation	organic material	carbon black	1333-86-4	0.082	0.07		672	
	plastics	epoxy resin	-	5.797	4.77		47699	
	inorganic material	silicondioxide	60676-86-0	34.948	28.75	33.59	287541	335912
leadfinish	non noble metal	tin	7440-31-5	1.452	1.19	1.19	11944	11944
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1362	1362
solder	noble metal	silver	7440-22-4	0.072	0.06		596	
	non noble metal	tin	7440-31-5	0.058	0.05		476	
	non noble metal	lead	7439-92-1	2.765	2.28	2.39	22752	23824
CLIP plating	noble metal	silver	7440-22-4	1.289	1.06	1.06	10609	10609
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		93	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	copper	7440-50-8	11.320	9.31	9.32	93137	93258
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		184	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	copper	7440-50-8	22.292	18.34	18.37	183408	183647
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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